



Material Content Data Sheet



Sales Product Name		ICE3BR0665J		Issued		24. January 2018			
MA#		MA001029928							
Package		PG-DIP-8-15		Weight*		551.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.508	1.54	1.54	15416	15416	
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		97		
	non noble metal	zinc	7440-66-6	0.213	0.04		387		
	non noble metal	iron	7439-89-6	4.266	0.77		7730		
wire	non noble metal	copper	7440-50-8	173.237	31.39	32.21	313878	322092	
	noble metal	gold	7440-57-5	0.389	0.07	0.07	705	705	
	encapsulation	organic material	carbon black	1333-86-4	1.773	0.32		3212	
encapsulation	plastics	epoxy resin	-	47.870	8.67		86733		
	inorganic material	silicondioxide	60676-86-0	304.953	55.25	64.24	552524	642469	
leadfinish	non noble metal	tin	7440-31-5	7.496	1.36	1.36	13581	13581	
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1451	1451	
glue	plastics	epoxy resin	-	0.414	0.08		750		
	noble metal	silver	7440-22-4	1.952	0.35	0.43	3536	4286	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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